



PerF≝T[™]Power Transistor

FEATURES

- Excellent FOM
- Reliability meets AEC-Q101 requirements
- Wettable flank leads for enhanced AOI
- 100% UIS and Rg tested
- 175°C operating junction temperature
- RoHS Compliant
- Halogen-free

KEY PERFORMANCE PARAMETERS				
PARAMETER		VALUE	UNIT	
V _D	S	100	V	
D (22.2.)	V _{GS} = 10V	25		
R _{DS(on)} (max)	V _{GS} = 7V	30	mΩ	
Q_g	V _{GS} = 10V	8.4	nC	



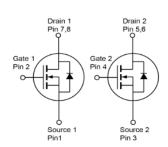




APPLICATIONS

- Solenoid and motor drivers
- DC-DC converters
- Load Switch
- SMPS





Note: MSL 1 (Moisture Sensitivity Level) per J-STD-020

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)				
PARAMETER Drain-Source Voltage Gate-Source Voltage		SYMBOL	100 ±20	UNIT
		V _{DS}		V
		V _{GS}		
Continuous Drain Current	T _C = 25°C		31	
	T _C = 100°C	I _D	22	Α
	T _A = 25°C		7.4	
Pulsed Drain Current (Note 1)		Ірм	124	А
Single Pulse Avalanche Current (Note 2)	I _{AS}	7	А
Single Pulse Avalanche Energy (Note 2)		Eas	7.3	mJ
Total Power Dissipation	T _C = 25°C		54	14/
	T _C = 125°C	P _D	18	W
Operating Junction and Storage Temperature Range		T _J , T _{STG}	- 55 to +175	°C

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	LIMIT	UNIT	
Junction to Case Thermal Resistance	Rejc	2.8	°C/W	
Junction to Ambient Thermal Resistance (Note 3)	RөJA	50	°C/W	

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Notes:

- 1. Pulse Width ≤ 100µs.
- 2. L = 0.3mH, VGS = 10V, RG = 25 Ω , Starting TJ = 25 $^{\circ}$ C.
- 3. Device on a PCB FR4 with 1 in² (single layer, 2 oz thickness) copper area for drain connection.

PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static		•				
Drain-Source Breakdown Voltage	$V_{GS} = 0V$, $I_D = 1mA$	BV _{DSS}	100			V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	V _{GS(TH)}	2.4	3	3.6	V
Gate Body Leakage	$V_{GS} = \pm 20V, V_{DS} = 0V$	I _{GSS}			±100	nA
	V _{GS} = 0V, V _{DS} = 100V	IDSS			1	μA
Drain-Source Leakage Current	V _G S = 0V, V _D S = 100V T _J = 125°C				100	
Drain-Source On-State Resistance	1/ 40// 1 45.54	_		20	25	mΩ
(Note 4)	V _{GS} = 7V, I _D = 15.5A	R _{DS(on)}		23	30	
Forward Transconductance (Note 4)	$V_{DS} = 10V, I_D = 3.9A$	G fs		14		S
Dynamic (Note 5)		•				•
Total Gate Charge	$V_{DS} = 50V, I_{D} = 7.4A,$ $V_{GS} = 7V$	Qg		6.2		nC
Total Gate Charge		Qg		8.4		
Gate-Source Charge	$V_{DS} = 50V, I_{D} = 7.4A,$	Q _{gs}		2.8		nC
Gate-Drain Charge	V _{GS} = 10V	Q _{gd}		2.3		
Input Capacitance	V _{DS} = 60V, V _{GS} = 0V, f = 1.0MHz	Ciss		513		
Output Capacitance		Coss		115		pF
Reverse Transfer Capacitance		Crss		18		
Gate Resistance	f = 1.0MHz	Rg		1.1		Ω
Switching (Note 6)						
Turn-On Delay Time	$V_{DD} = 50V, R_G = 6\Omega,$ $I_D = 7.4A, V_{GS} = 10V$	t _{d(on)}		6.5		
Turn-On Rise Time		t _r		16		
Turn-Off Delay Time		t _{d(off)}		10		ns
Turn-Off Fall Time		t _f		5.9		
Source-Drain Diode						
Forward Voltage (Note 4)	I _S = 15.5A, V _{GS} = 0V	V _{SD}			1.1	V
Reverse Recovery Time	Is = 7.4A,	t _{rr}		40		ns
Reverse Recovery Charge	di/dt = 100A/µs	Qrr		47		nC

Notes:

- 4. Pulse test: Pulse Width $\leq 300 \mu s$, duty cycle $\leq 2\%$.
- 5. Defined by design. Not subject to production test.
- 6. Switching time is essentially independent of operating temperature.

ORDERING INFORMATION

ORDERING CODE	PACKAGE	PACKING
TSM250NH10DCR RL	G PDFN56U Dual	2,500pcs / 13" Reel

Transfer Characteristics



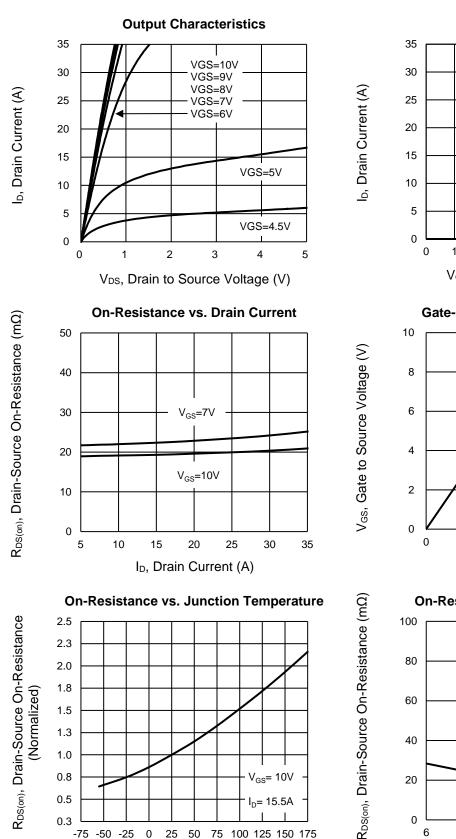
CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

0.8

0.5

0.3



 $V_{GS} = 10V$

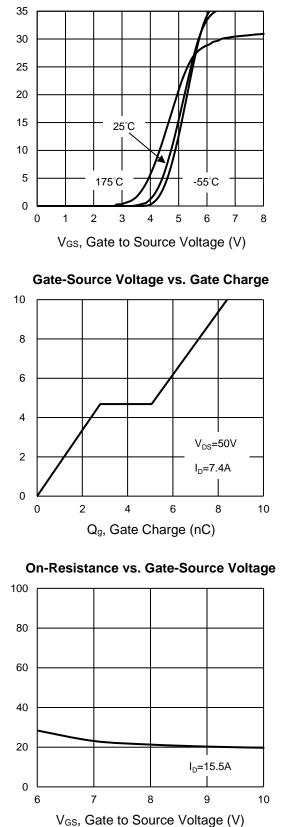
I_D= 15.5A

3

75 100 125 150 175

25 50

T_J, Junction Temperature (°C)

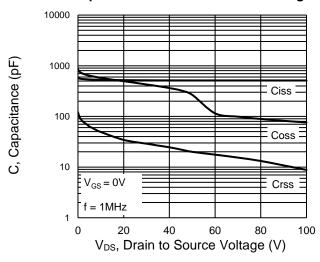




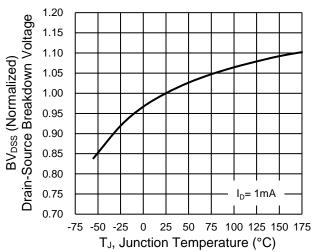
CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

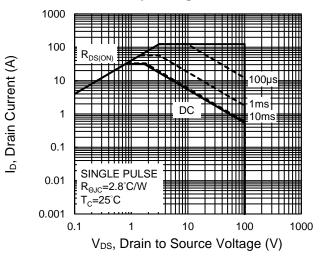




BV_{DSS} vs. Junction Temperature



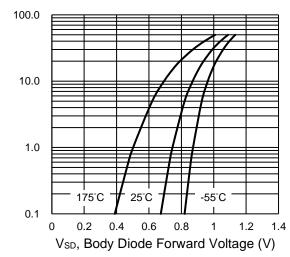
Maximum Safe Operating Area, Junction-to-Case



Normalized Effective Transient

Thermal Impedance, Zeuc

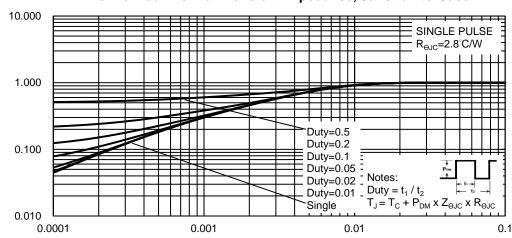
Source-Drain Diode Forward Current vs. Voltage



Normalized Thermal Transient Impedance, Junction-to-Case

Reverse Drain Current (A)

<u>,</u>

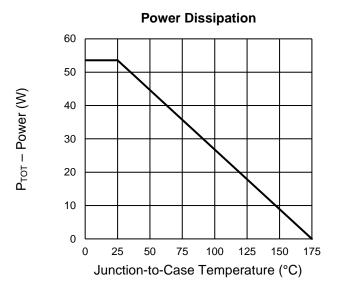


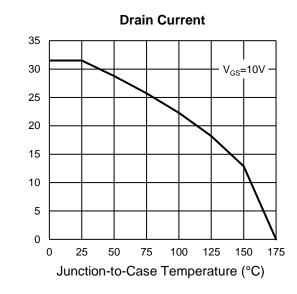
t, Square Wave Pulse Duration (sec)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

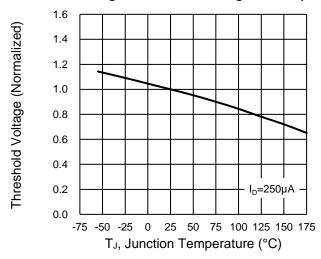




I_D-Drain Current (A)

5

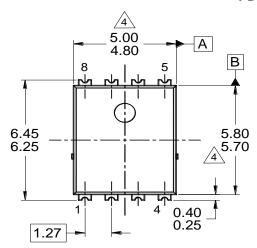
Normalized gate threshold voltage vs Temperature

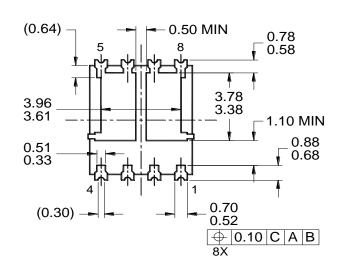


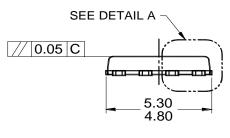


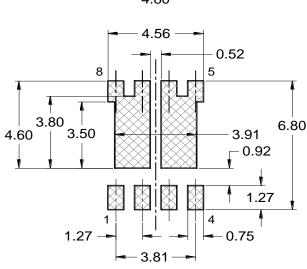
PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

PDFN56U Dual









SUGGESTED PAD LAYOUT

(REFERENCE ONLY)

0.90MIN

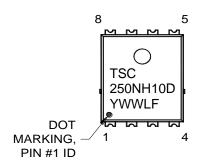
1.10
0.90

0.30
0.20

PLATED AREA

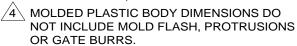
SEATING PLANE

DETAIL A
(SCALE 2:1)



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PACKAGE OUTLINE REFERENCE: JEITA ED-7500B, EIAJ SC-111CB.



5. DWG NO. REF: HQ2SD07-PDFN56UD-032 REV B.

MARKING DIAGRAM

250NH10D = Device marking Y = Year code

WW = Week code (01~52)
L = Lot code (1~9,A~Z)
F = Factory code



Taiwan Semiconductor

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